Abstract

Supply mechanism for the chuck of an integrated circuit dicing device

A system for dicing substrates to singulate integrated circuit units within in them includes a dicing machine (Z) which operates with a chuck table (4). A lifting assembly (Ax,Ay) deposits substrates to be singulated onto the chuck table (4) at substantially the same time as it removes previously singulated units from the chuck table (4).

[Fig. 1]

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